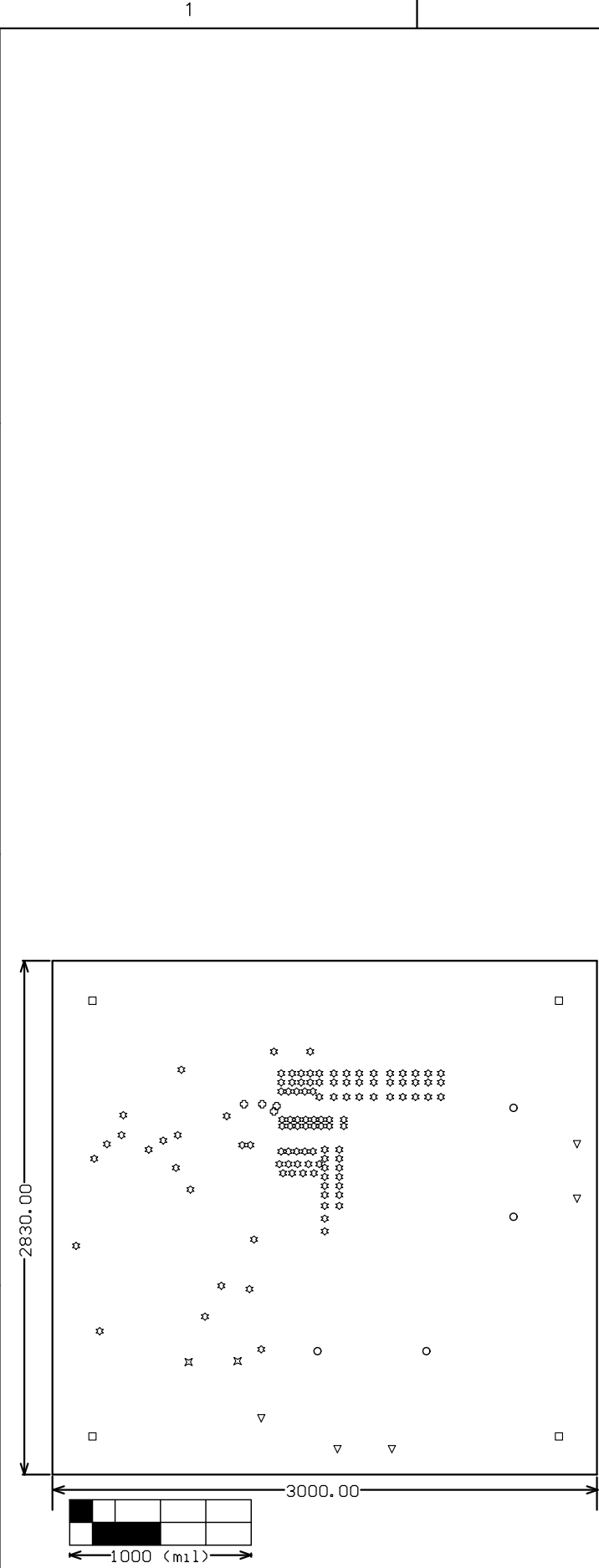


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Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
⊕	4	8mil (0.2032mm)	PTH	Round
☆	111	10mil (0.254mm)	PTH	Round
✕	2	24mil (0.6096mm)	PTH	Round
▽	5	63mil (1.6002mm)	PTH	Round
□	4	125.984mil (3.2mm)	PTH	Round
○	4	214.567mil (5.45mm)	PTH	Round
	130 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M50 T50c Krypt			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM	TEXAS INSTRUMENTS	

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Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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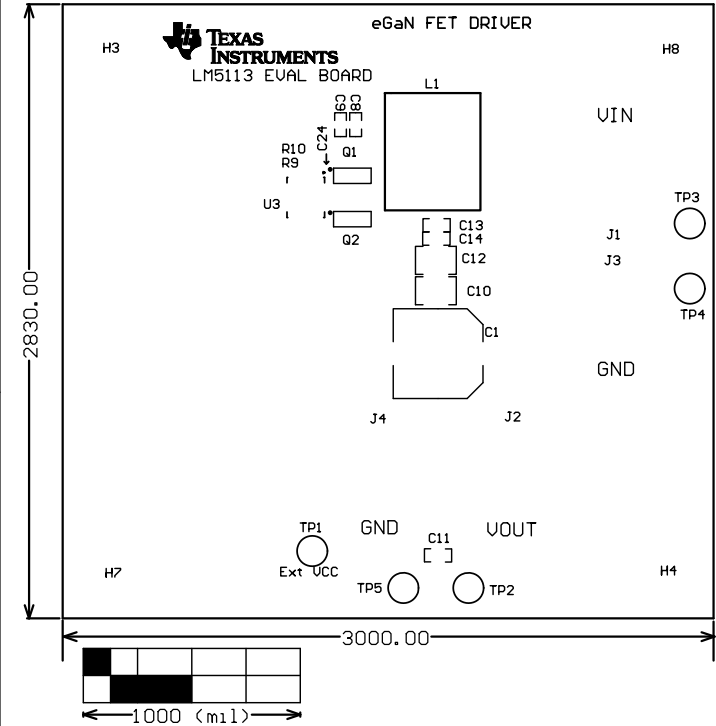


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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M02 Top Sheet			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)

☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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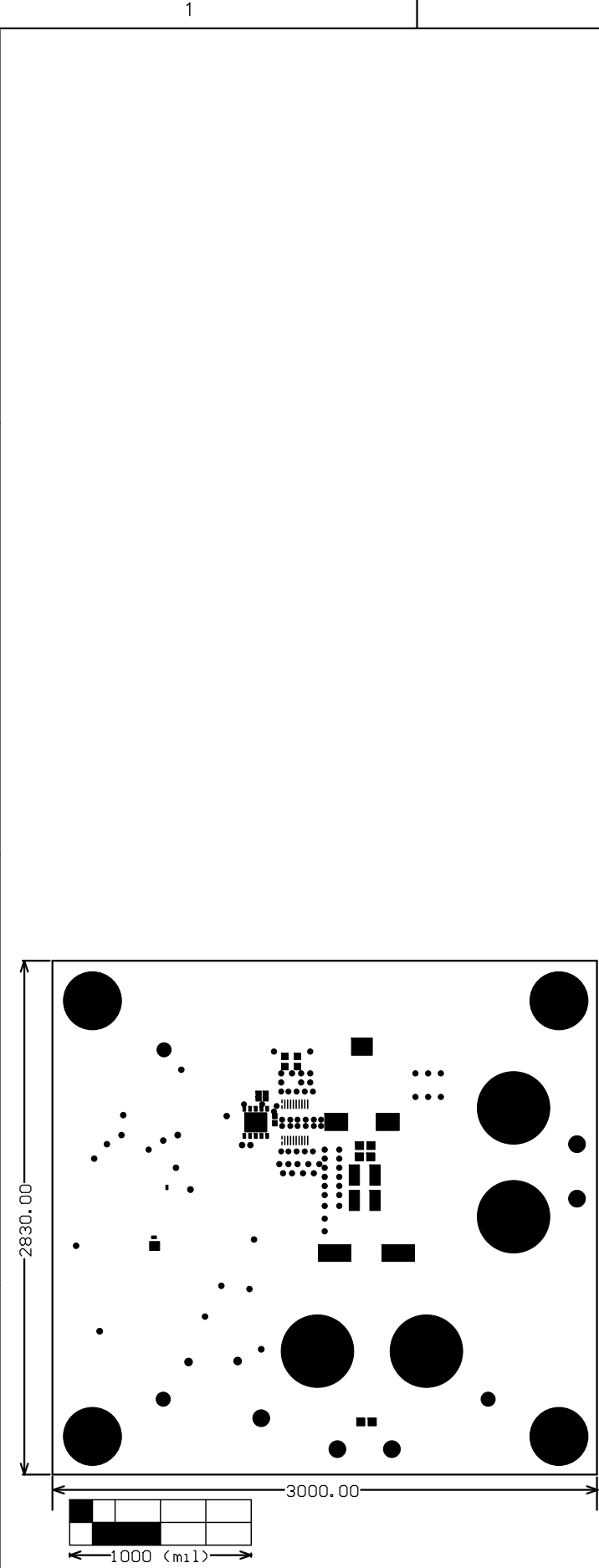
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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M02 Top Solder Mask			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM	TEXAS INSTRUMENTS	

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:  
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER  
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER  
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-  
COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A  
DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER  
BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER  
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER  
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE  
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER  
ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

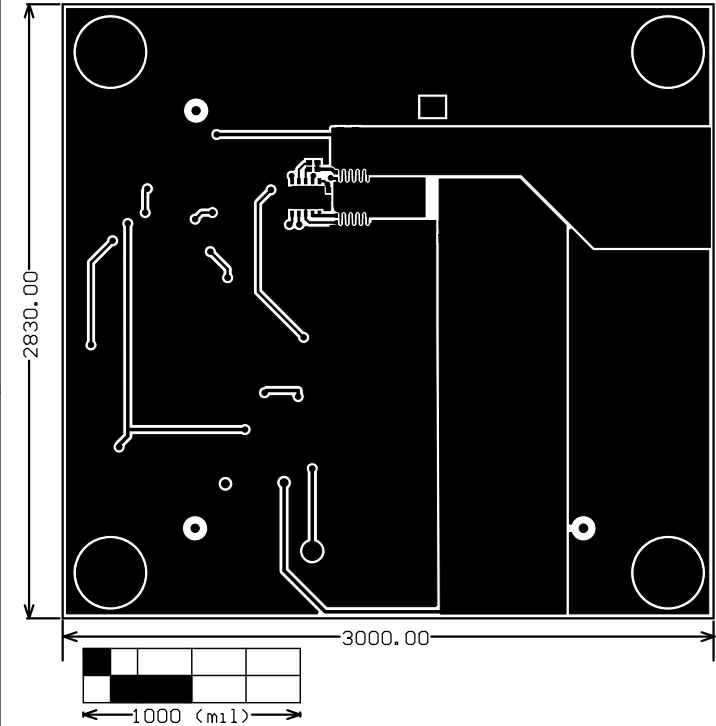
ALTUM DESIGNER VERSION:  
10.0.0.27009

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M02 Top Solder Mask			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS  
INSTRUMENTS

PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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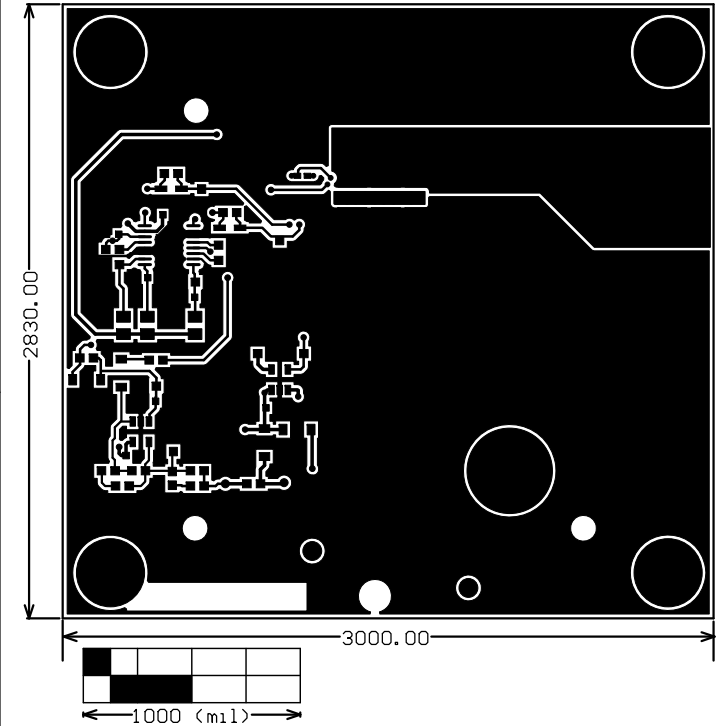
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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M50 T50b K50p			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

LAYOUT BY:

SCALE: 1.00

ALTUM DESIGNER VERSION:  
10.0.0.27009

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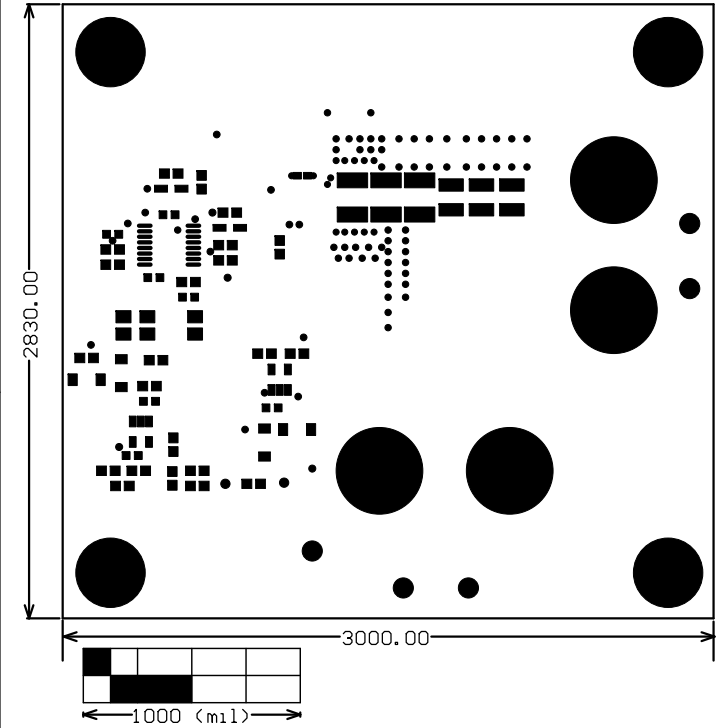


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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SU600663	REV: B	
LAYER NAME = M02 Top Silkscreen			
PLOT NAME = LM5113LLPEVB.GM11	GENERATED : 11/9/2013 10:25:27 PM		TEXAS INSTRUMENTS

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Layer Stack Up Detail for: LM5113LLPEVB.PcbDoc

Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material	Dielectric Constant	Dielectric Type
Top Solder Mask	(.GTS)		0.4mil	Solder Resist	3.50	
Top Layer	(.GTL)	2.8mil	59.2mil	FR-4 High Tg	4.80	Core
Bottom Layer	(.GBL)	2.8mil				
Bottom Solder Mask	(.GBS)		0.4mil	Solder Resist	3.50	

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
3000MIL X 2830MIL

Number of Layers : 2  
MIN. TRACK WIDTH: 8 MIL  
MIN. CLEARANCE: 8 MIL  
MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C  
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

☐ FR-4 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2  
☐ OTHER +/-

COPPER THICKNESS (FINISHED):  
OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)  
INNER SIGNAL: ☐ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☒ N/A

DRILLING:  
REFERENCE: ☒ AS SHOWN ☒ NC\_DRILL FILES  
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:  
SILKSCREEN: ☒ TOP ☒ BOTTOM  
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER  
SOLDER RESIST COLOR:  
☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)  
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1  
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3  
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:  
MICROSECTION: ☐ YES  
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER  
MANUFACTURER'S ID/LOGO: ☐ RAIL ☐ METAL ☒ SILK

TEXAS INSTRUMENTS

PROJECT TITLE:  
LM5113LLP Evaluation Board

DESIGNED FOR:  
Public Release

FILE NAME:  
LM5113LLPEVB.PcbDoc

MODIFIED BY:  
Krypton Solutions

SCALE: 1.00

LAYOUT BY:

ALTUM DESIGNER VERSION:  
10.0.0.27009

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